With facilities on both East and West Coasts, Valley Design offers increased capacity in advanced high-speed CNC dicing, cutting and sawing, enabling us to provide a complete spectrum of shapes and materials.

Patterned Wafers • Circuited Substrates • Optical Gratings • Semiconductors
Patterned Optics • Chip Capacitors • Step and Repeat Patterns • Beamsplitters
Bonded Wafers • DWDM Filters • Bandbass Filters • Ceramic Hybrids
Smart Cards • Laser Diodes • Slotted Heat Sinks • Chromium Lithography
Glass/Metal Rods • Metal Coated Substrates • Optical Coated Wafers
IC Chips • Slots/Steps • Cubes • Pyramids • Towers • Hexagons • V-Grooves
MEMS Wafers • Triangles • Octagons • Scribe & Break • Scored Pyramids

Alumina • Aluminum Nitride • BK7 • Cadmium Telluride • Ceramics • Ferrites
Fused Silica • Gallium Arsenide • Gallium Nitride • Gallium Phosphide • Glass
Indium Phosphide • Infrared Materials
Lithium Niobate • Polarcor • Pyrex • PZT
Quartz • Sapphire • Silicon

SALES & CUSTOMER SERVICE
Phone: 831.420.0595        FAX: 831.420.0592
e-mail: sales@valleydesign.com

WEST
Santa Cruz, CA

EAST
Shirley, MA
Don’t Leave Your Dicing Jobs to Chance!

Valley Design now offers expanded capacity and service with our newly expanded 30,000 sq.ft. facilities in Santa Cruz, CA and Shirley, MA. With over 30 years of precision dicing and machining experience, Valley Design is fully equipped to handle even your most challenging projects.

Our fully programmable dicing saws are equipped with 200X microscopes and video screens to ensure precision alignment.

Contact us today for a quote to meet your specifications
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YOU CAN BET ON US!

CAPABILITIES
- Chip sizes as small as .005” sq.
- Kerf as low as 20 microns
- Material sizes up to 8” x 18” any thickness
- Ultra-thin materials diced to 10 microns thick with edge chipping less than 2 microns
- Mounting methods include UV cured or sticky tape, hard carrier, or wax mount
- Blade inventory includes diamond and super abrasives in all sizes and grits using resin bond, metal bond or plated technology

What Else Does Valley Design Do?

Valley Design, an ISO 9001:2000 certified company, has been a leader in materials processing for over 25 years. Valley offers precision lapping, polishing, dicing, edge/angle polishing, thinning, fiber array polishing, bonding, coating, grinding, shaping and wafering services. The company specializes in ultra-thin (as thin as 12.5 microns), ultra-flat (1/20 Wave) super-polishing (< 10/5 scratch/dig or 5-10 Angstroms) and tight tolerances (+/- 1 micron).

Applications and products include substrates, windows, wafers, stock and custom flat optical components, subassemblies, beam splitters, polarizers, DWDM filter substrates, glass rods/blocks/spacers, lenses, mirrors, prisms, SEMI standard dummy wafers, solar cells, waveguides, wedges, laser diodes.

Valley enjoys extensive experience with a wide variety of materials, and is also willing to work with proprietary materials. Valley routinely processes Fused Silica, Quartz, Optical Glass, ALN, Pyrex, 99.6% and 96% Alumina, Sapphire, AF45, BK7, B270, D263, LASFN9, 1737, 7070, Ceramics, GaAs, InP, ZnS, ZnSe, PZT, PLZT, Lithium Niobate, Borosilicates, Soda Lime, Crystals, Silicon and Metals. The company also has extensive stock in Fused Silica, Silicon, Soda Lime, Aluminum Nitride, Sapphire and 96%/99.6% Alumina.

Is your dicing saw down? If you have a dicing emergency... CALL US! We offer backup services with delivery as fast as 24 hours in prototype or production quantities.